

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5629899

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SUNNA CHUNG	07/18/2019
RYAN PARK	07/18/2019
JIN CHAE	07/18/2019
MATTHEW WHITLOCK	07/18/2019
JONATHAN LIE	07/18/2019
ATHENS OKOREN	07/18/2019
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16116847
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NAME OF SUBMITTER:	BRENDY LYNN BELONY
SIGNATURE:	/BRENDY LYNN BELONY/
DATE SIGNED:	07/22/2019

PATENT

Total Attachments: 2

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ASSIGNMENT BY INVENTORS

This Assignment is by **Sunna Chung; Ryan Park; Jin Chae; Matthew Whitlock; Jonathan Lie and Athens Okoren** (the "Assignors"). The Assignors invented one or more certain inventions (the "Invention(s)") described in an application for Letters Patent of the United States titled **SEPARATORS FOR HANDLING, TRANSPORTING, OR STORING SEMICONDUCTOR WAFERS**, and filed on **August 29, 2018** as U.S. Application No. **16/116,847** (the "Application").

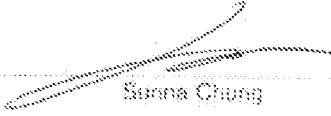
Daewon Semiconductor Packaging Industrial Company, a corporation having its principal place of business at **2350 Mission College Blvd., Suite 900, Santa Clara, CA 95054** (the "Assignee"), desire to acquire the entire right, title and interest in and to the Invention(s) and the Application, and in and to any patents (collectively, "Patents") that may be granted for the Invention(s) in the United States or in any foreign countries.

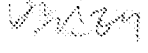
For valuable consideration, the receipt and sufficiency of which Assignors acknowledge, Assignors hereby sell, assign, and transfer to Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to: the Invention(s), the Application, and any Patents; any divisions, continuations, and continuations-in-part of the Application and any other application claiming priority rights from the Application; any reissues, reexaminations, or extensions of any and all Patents; the right to file foreign applications directly in the name of Assignee; and the right to claim priority rights deriving from the Application (collectively, the "Rights"). Assignors warrant that Assignors own the Rights, and that the Rights are unencumbered. Assignors also agree to not sign any writing or do any act conflicting with this assignment, and, without further compensation, sign all documents and do such additional acts as Assignee deem necessary or desirable to: perfect Assignee's enjoyment of the Rights; conduct proceedings regarding the Rights, including any litigation or interference proceedings; or perfect or defend title to the Rights. Assignors request the Commissioner of Patents to issue any Patent of the United States that may be issued on the Invention(s) to Assignee. This Assignment may be executed in counterparts.

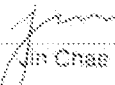
See page 2 for signatures

Application Serial No. 147119 887


Attorney Docket No. 129887-8903 12302

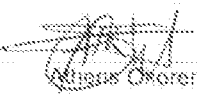
Date: 7/18/2019 Signature: 
Sunna Chung

Date: 7/18/2019 Signature: 
Ryan Park

Date: 7/18/2019 Signature: 
Jin Chae

Date: 7/18/2019 Signature: 
Matthew Whillock

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Chae O'Brien